

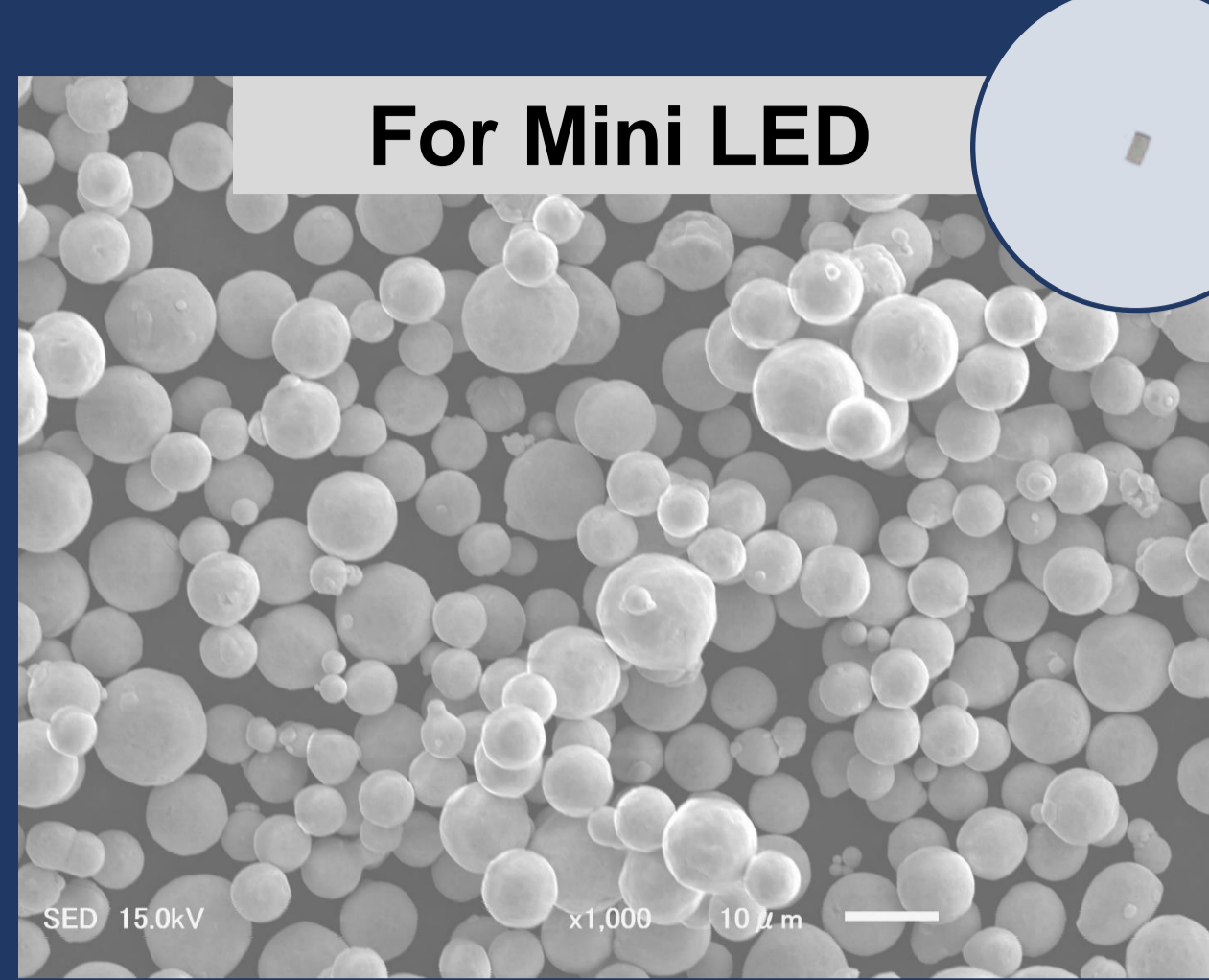
Mini與Micro LED焊接用錫膏與助焊劑

Solder Paste & Flux for Mini & Micro LED Soldering



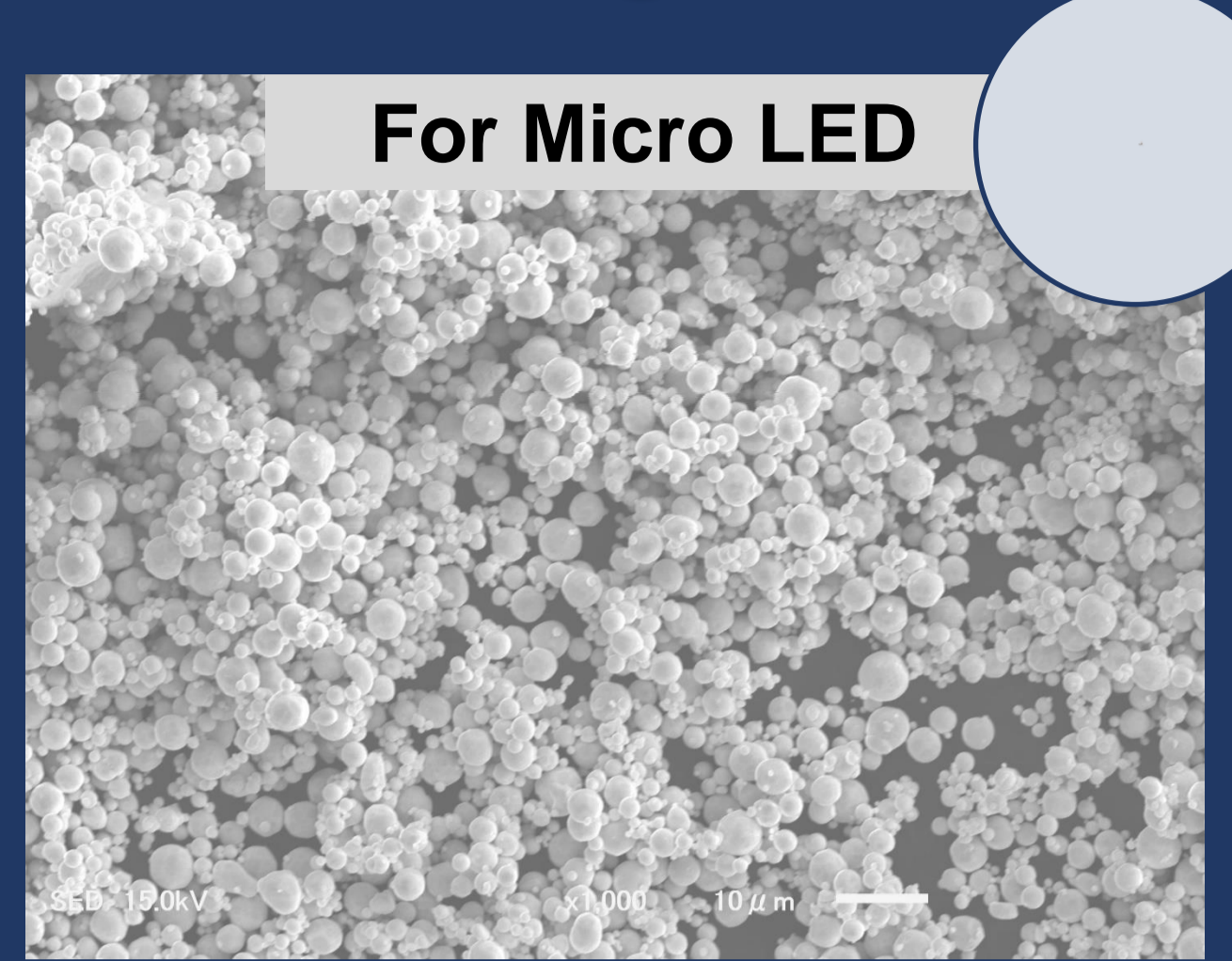
For SMT

Type 4 : 38-20 μm



For Mini LED

Type 7 : 11-2 μm



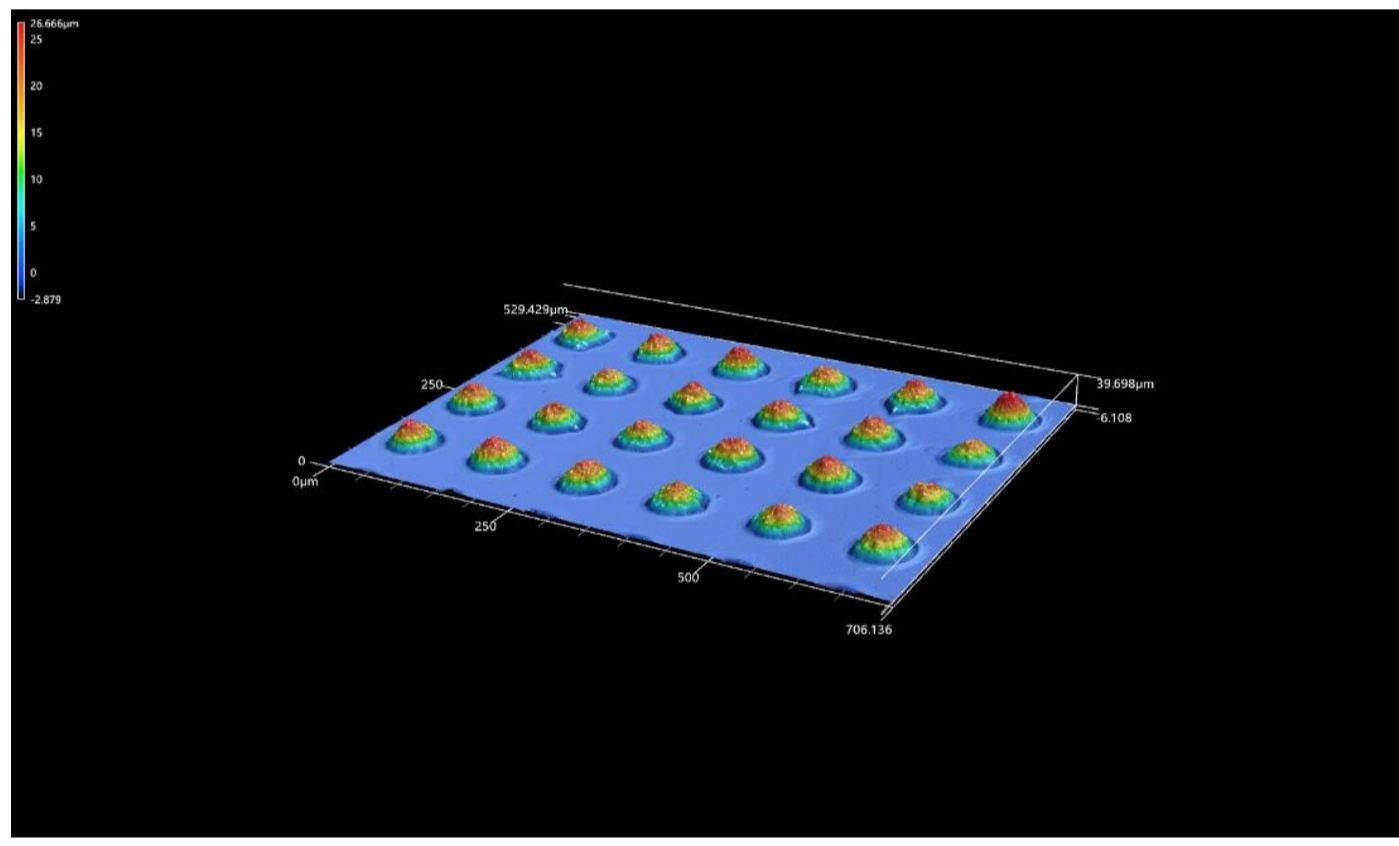
For Micro LED

Type 9 : 5-1 μm

Mini LED 實裝

微細開口印刷量穩定

Print Volume Stability in Fine Printing

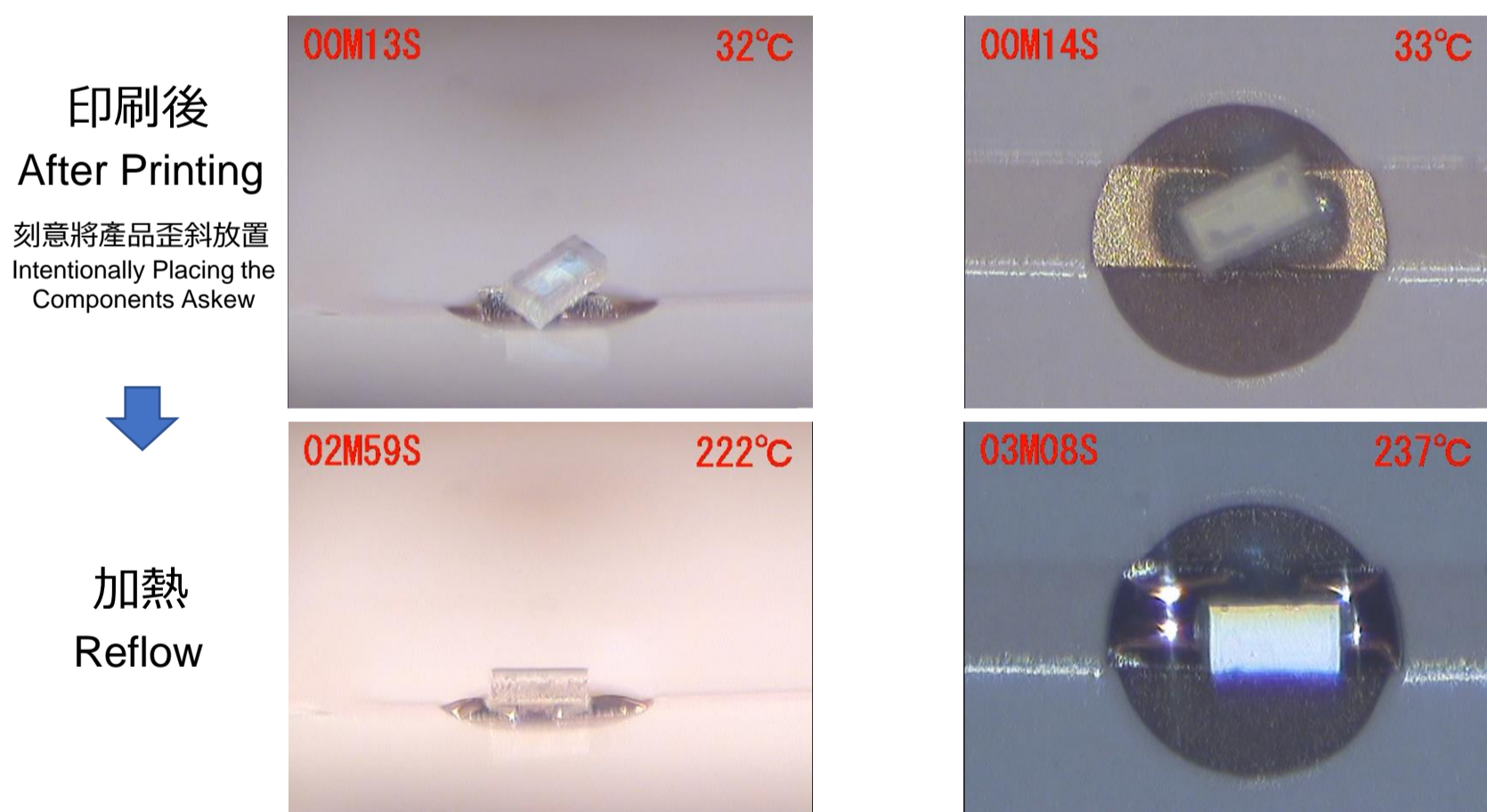


鋼板開口 $\phi 60\mu\text{m}$ t25 μm
Mask Opening $\phi 60\mu\text{m}$ t25 μm

印刷形狀一致且高度穩定
Consistent and Highly Stable Print Shape

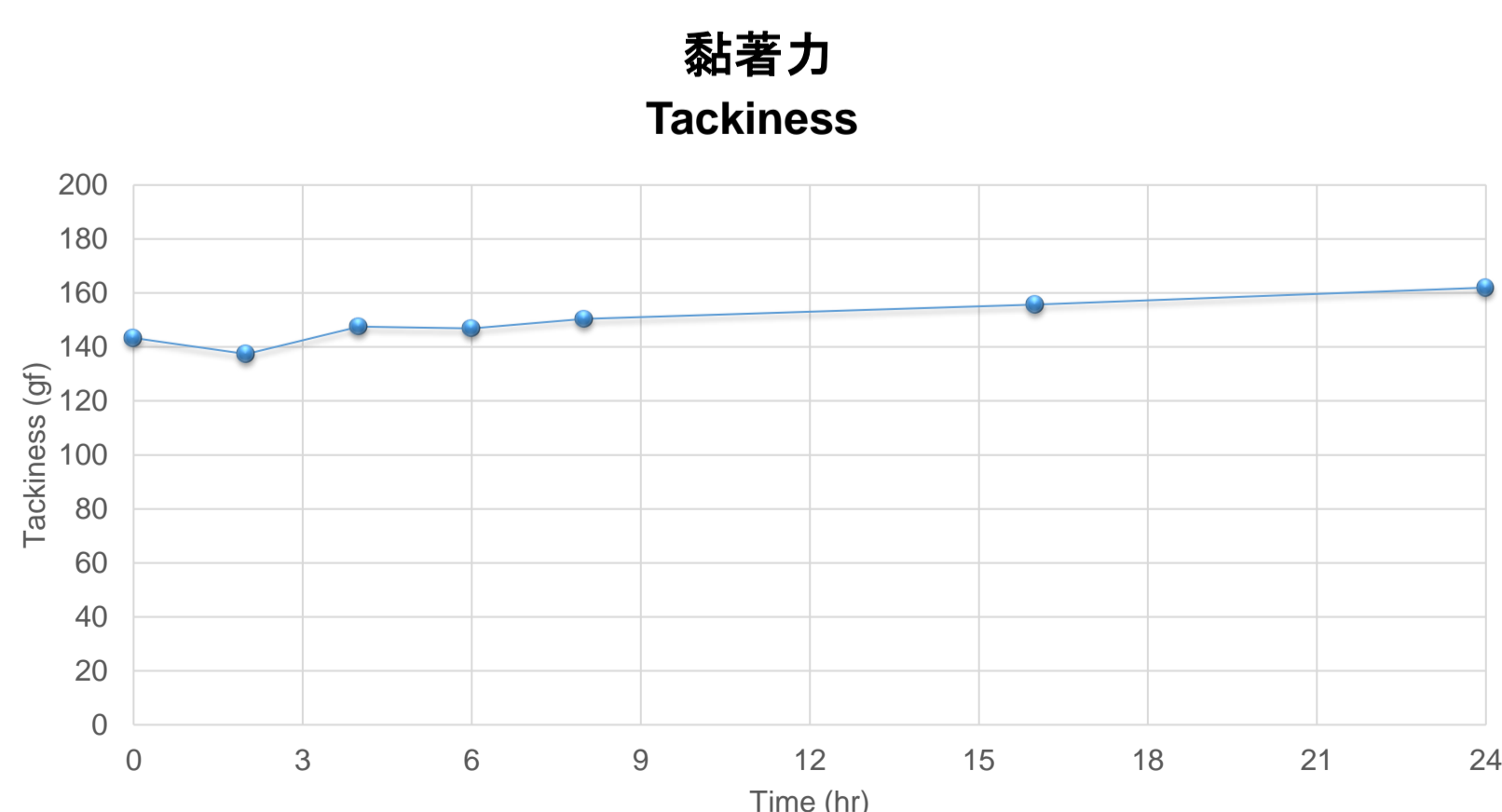
熔融性良好產品自我對位

Self-Alignment of Components with Good Meltability



印刷後放置24小時維持黏著力

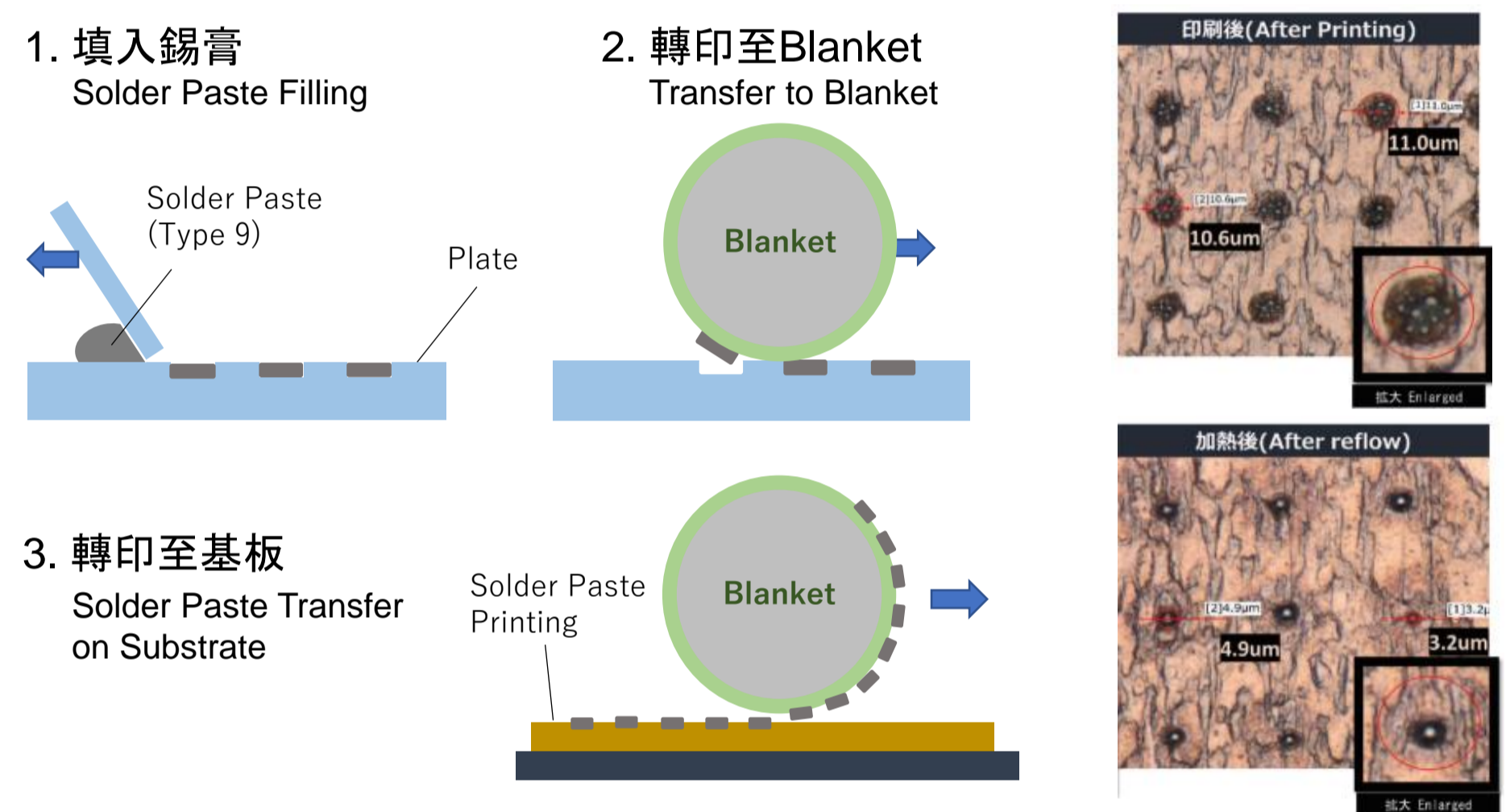
Maintenance of Tackiness Over 24hr After Printing



Micro LED 實裝

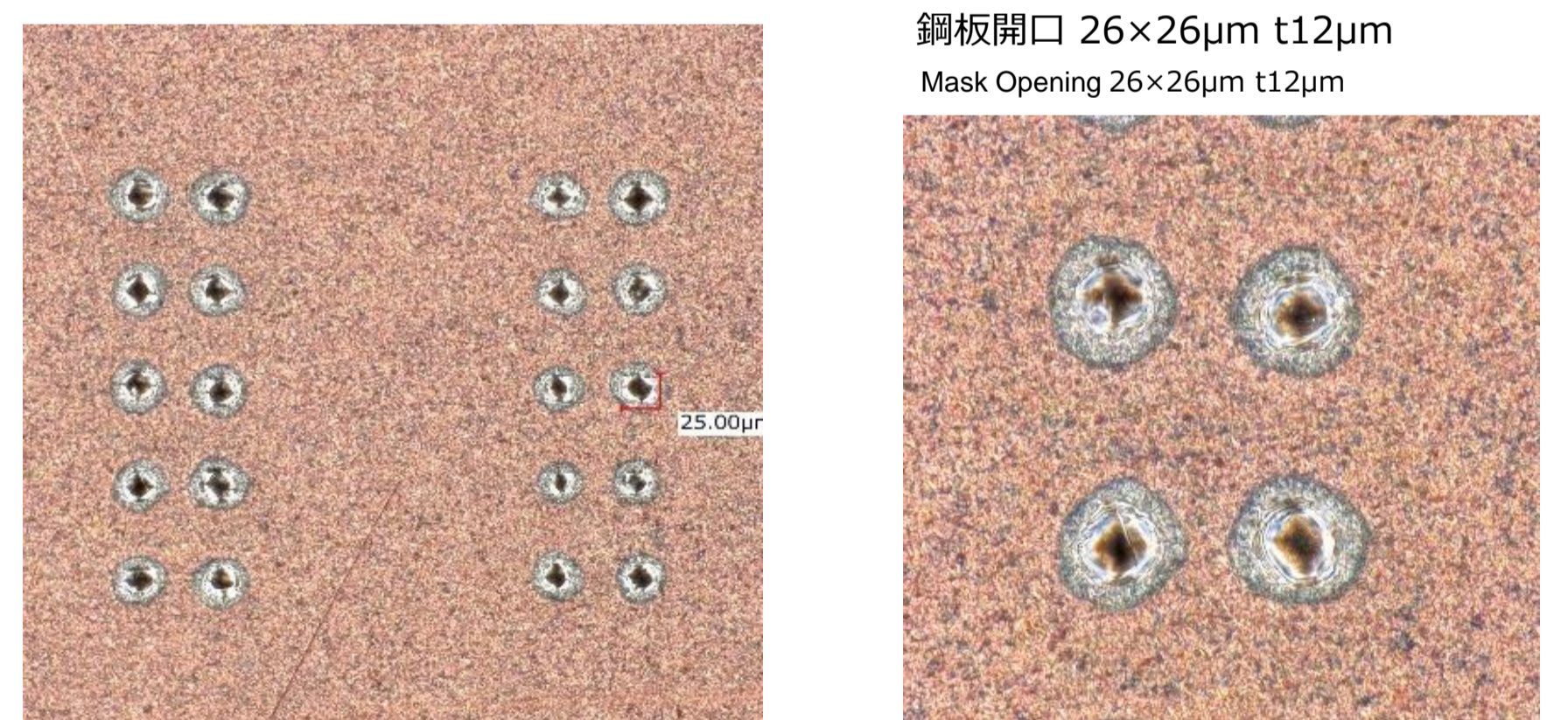
超微細接合的焊料供應工法

Solder Supply Method for Ultrafine Soldering



確保超微細粉末的熔融性

Ensuring the Meltability of Ultrafine Powders



錫凸塊用助焊劑

Flux for Solder Bump

確認加熱後無助焊劑殘留
Verify No Flux Residue After Reflow

